Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(method with positioning with bond with pads).pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:17
L2	12	(method with positioning with bond with pads).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:22
L3	6	("5498767" | "5801450" | "5962926" | "6110823" | "6150727").PN. OR ("6405357").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:18
L4	3066	(method with wire with bonding).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:22
L5	234	4 and "438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:23
L6	10	5 and pad with coordinates	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:23
L7	2	"20050067678".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L8	2037	(438/14).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 11:30
L9	800	(438/15).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 11:30

L10	2561	L8 L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L11	1	L10 and learn$3 near touch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L12	5	L10 and determin$3 near3 pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L13	0	L10 and dummy with pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L14	177	L10 and pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L15	1341	wire near2 bond$3 with pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L16	5	L15 and L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L17	31	(wire with bonding with operation).clm. and "438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L18	256	wafer with bonding with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30

L19	145	L18 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L20	40	L19 and sensing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L21	2641	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 13:49
L22	435	(438/617).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 11:30
L23	96	L22 and pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L24	45	L22 and pad near4 (position$3 coordinate)	USPAT	OR	ON	2006/02/02 11:30
L25	2958	L22 L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L26	26	L25 and dummy with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L27	17	L25 and dummy with pad	USPAT	OR	ON	2006/02/02 11:30
L28	51	L25 and (dummy with pad anchors)	USPAT	OR	ON	2006/02/02 11:30
L29	8	("5700735" | "5734200" | "5736791" | "5773899" | "5962919" | "6002179").PN. OR ("6165886"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L30	98	pad near4 height and L25	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L31	66	pad near4 height and L25	USPAT	OR	ON	2006/02/02 11:30

L32	107	learn$3 near touch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L33	1	learn$3 near touch$3 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L34	23	learn$3 near touch$3 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L35	135	bonding with tool and L25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L36	90	bonding with tool and L25	USPAT	OR	ON	2006/02/02 11:30
L37	76	L35 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L38	69	L37 and wir$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L39	44	L37 and wir$3	USPAT	OR	ON	2006/02/02 11:30
L40	5	bonding with tool same dummy near3 pad	USPAT	OR	ON	2006/02/02 11:30
L41	2	bonding with tool same dummy near3 pad	US-PGPUB	OR	ON	2006/02/02 11:30
L42	5	bonding with tool same dummy near3 pad	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L43	1	1989-321630.NRAN.	DERWENT	OR	ON	2006/02/02 11:30
L44	10	bonding and tool and dummy and pad	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L45	17	height with pad with sensing	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30

L46	10	height with pad with sensing	US-PGPUB	OR	ON	2006/02/02 11:30
L47	27	height with pad with sensing	USPAT	OR	ON	2006/02/02 11:30
L48	95	height with pad with tool	USPAT	OR	ON	2006/02/02 11:30
L49	36	height near5 pad with tool	USPAT	OR	ON	2006/02/02 11:30
L50	0	pad with coodinate	USPAT	OR	ON	2006/02/02 11:30
L51	1017	pad with coordinate	USPAT	OR	ON	2006/02/02 11:30
L52	36	pad near2 coordinate and wafer and tool	USPAT	OR	ON	2006/02/02 11:30
L53	571	reference near3 pad and tool	USPAT	OR	ON	2006/02/02 11:30
L54	42	reference near3 pad and tool and "438"/$.ccls.	USPAT	OR	ON	2006/02/02 11:30
L55	5	bonding with tool same dummy with pad	USPAT	OR	ON	2006/02/02 11:30
L56	2	pad with coordinate and dummy adj pad	USPAT	OR	ON	2006/02/02 11:30
L57	34	pad with height same bonding with tool	USPAT	OR	ON	2006/02/02 11:30
L58	11513	pad near2 position	USPAT	OR	ON	2006/02/02 11:30
L59	133	L58 and bonding near3 tool	USPAT	OR	ON	2006/02/02 11:30
L60	23	L59 and pad with height	USPAT	OR	ON	2006/02/02 11:30
L61	263	L21 and pad with (coordinate positon location)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L62	163	L61 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L63	173	L61 and wir$4 near2 bond$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L64	67	L22 and pad with (coordinate positon location)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L65	3066	(Wire with bonding with method).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30

L66	3	L65 and (dummy with pad).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L67	2	L65 and (dummy with pad).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L68	7	L65 and (dummy with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L69	0	determine with positon with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L70	961	determine with position with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L71	13	L70 and bonding with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L72	10	L70 and wire with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L73	79	("4342090" | "4674670" | "4765531" | "5052606" | "5082165" | "5108023").PN. OR ("5307978"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L74	1132	pad with (pressure stress) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L75	5	L22 and pad with (pressure stress) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L76	5	L22 and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30

L77	9	L21 and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L78	89	"438"/$.ccls. and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L79	81	(438/120).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 11:30
L80	3317	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 11:30
L81	215	L80 and pad with (pressure stress shock)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L82	224	L80 and pad with (pressure stress shock)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L83	135	L82 and (wire wiring) with (bond bonding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L84	30736	(coordinate or position or x-y) same pad same (wir$3 or bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L85	1673	(coordinate or position or x-y) same pad same (wir$3 or bond$3)same tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L86	112	L85 and pad with height	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30

L87	11	L85 and pad with dummy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:30
L88	25	("5498767").URPN.	USPAT	OR	ON	2006/02/02 11:30
L89	5	("5498767" | "5801450" | "5962926" | "6110823" | "6150727").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L90	1	("6405357").URPN.	USPAT	OR	ON	2006/02/02 11:30
L91	2	("5155065" | "5245214").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L92	2	("5155065" | "5245214").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L93	2	("5155065" | "5245214").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 11:30
L94	6156	(wire and bonding and tool and coordinate pad and height).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:45
L95	2	(wire and bonding and tool and coordinate and pad and height).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:45
L96	2	(wire and bonding and tool and coordinate and pad and height).clm.	US-PGPUB	OR	ON	2006/02/02 11:46
L97	2	(wire and bonding and coordinate and pad and height).clm.	US-PGPUB	OR	ON	2006/02/02 11:46
L98	10	(wire and bonding and tool and pad and height).clm.	US-PGPUB	OR	ON	2006/02/02 11:52
L99	5	(wire and bond$3 and tool and pad and coordinate).clm.	US-PGPUB	OR	ON	2006/02/02 11:53
L100	10	(wire and bond$3 and tool and pad and height).clm.	US-PGPUB	OR	ON	2006/02/02 11:53
L112	2	"20050067678".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L113	2037	(438/14).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 14:22

L114	800	(438/15).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 14:22
L115	2561	L8 L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L116	1	L10 and learn$3 near touch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L117	5	L10 and determin$3 near3 pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L118	0	L10 and dummy with pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L119	177	L10 and pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L120	1341	wire near2 bond$3 with pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L121	5	L15 and L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L122	31	(wire with bonding with operation). clm. and "438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22

L123	256	wafer with bonding with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L124	145	L18 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L125	40	L19 and sensing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L126	2641	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 14:22
L127	435	(438/617).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 14:22
L128	96	L22 and pad near4 (position$3 coordinate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L129	45	L22 and pad near4 (position$3 coordinate)	USPAT	OR	ON	2006/02/02 14:22
L130	2958	L22 L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L131	26	L25 and dummy with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L132	17	L25 and dummy with pad	USPAT	OR	ON	2006/02/02 14:22
L133	51	L25 and (dummy with pad anchors)	USPAT	OR	ON	2006/02/02 14:22
L134	8	("5700735" | "5734200" | "5736791" | "5773899" | "5962919" | "6002179").PN. OR ("6165886"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22

L135	98	pad near4 height and L25	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L136	66	pad near4 height and L25	USPAT	OR	ON	2006/02/02 14:22
L137	107	learn$3 near touch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L138	1	learn$3 near touch$3 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L139	23	learn$3 near touch$3 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L140	135	bonding with tool and L25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L141	90	bonding with tool and L25	USPAT	OR	ON	2006/02/02 14:22
L142	76	L35 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L143	69	L37 and wir$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L144	44	L37 and wir$3	USPAT	OR	ON	2006/02/02 14:22
L145	5	bonding with tool same dummy near3 pad	USPAT	OR	ON	2006/02/02 14:22
L146	2	bonding with tool same dummy near3 pad	US-PGPUB	OR	ON	2006/02/02 14:22
L147	5	bonding with tool same dummy near3 pad	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L148	1	1989-321630.NRAN.	DERWENT	OR	ON	2006/02/02 14:22

L149	10	bonding and tool and dummy and pad	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L150	17	height with pad with sensing	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L151	10	height with pad with sensing	US-PGPUB	OR	ON	2006/02/02 14:22
L152	27	height with pad with sensing	USPAT	OR	ON	2006/02/02 14:22
L153	95	height with pad with tool	USPAT	OR	ON	2006/02/02 14:22
L154	36	height near5 pad with tool	USPAT	OR	ON	2006/02/02 14:22
L155	0	pad with coodinate	USPAT	OR	ON	2006/02/02 14:22
L156	1017	pad with coordinate	USPAT	OR	ON	2006/02/02 14:22
L157	36	pad near2 coordinate and wafer and tool	USPAT	OR	ON	2006/02/02 14:22
L158	571	reference near3 pad and tool	USPAT	OR	ON	2006/02/02 14:22
L159	42	reference near3 pad and tool and "438"/$.ccls.	USPAT	OR	ON	2006/02/02 14:22
L160	5	bonding with tool same dummy with pad	USPAT	OR	ON	2006/02/02 14:22
L161	2	pad with coordinate and dummy adj pad	USPAT	OR	ON	2006/02/02 14:22
L163	34	pad with height same bonding with tool	USPAT	OR	ON	2006/02/02 14:22
L164	11513	pad near2 position	USPAT	OR	ON	2006/02/02 14:22
L165	133	L58 and bonding near3 tool	USPAT	OR	ON	2006/02/02 14:22
L166	23	L59 and pad with height	USPAT	OR	ON	2006/02/02 14:22
L167	263	L21 and pad with (coordinate positon location)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L168	163	L61 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L169	173	L61 and wir$4 near2 bond$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22

L170	67	L22 and pad with (coordinate positon location)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L171	3066	(Wire with bonding with method).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L172	3	L65 and (dummy with pad).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L173	2	L65 and (dummy with pad).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L174	7	L65 and (dummy with pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L175	0	determine with positon with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L176	961	determine with position with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L177	13	L70 and bonding with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L178	10	L70 and wire with tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22

L179	79	("4342090" | "4674670" | "4765531" | "5052606" | "5082165" | "5108023").PN. OR ("5307978"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L180	1132	pad with (pressure stress) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L181	5	L22 and pad with (pressure stress) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L182	5	L22 and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L183	9	L21 and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L184	89	"438"/$.ccls. and pad with (pressure stress shock) with tool	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L185	81	(438/120).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 14:22
L186	3317	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 14:22
L187	215	L80 and pad with (pressure stress shock)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L188	224	L80 and pad with (pressure stress shock)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L189	135	L82 and (wire wiring) with (bond bonding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L190	30736	(coordinate or position or x-y) same pad same (wir$3 or bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22

L191	1673	(coordinate or position or x-y) same pad same (wir$3 or bond$3)same tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L192	112	L85 and pad with height	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L193	11	L85 and pad with dummy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:22
L194	25	("5498767").URPN.	USPAT	OR	ON	2006/02/02 14:22
L195	5	("5498767" | "5801450" | "5962926" | "6110823" | "6150727").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L196	1	("6405357").URPN.	USPAT	OR	ON	2006/02/02 14:22
L197	2	("5155065" | "5245214").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22
L198	2	("5155065" | "5245214").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:22